

ABSTRACT

Sub  
a6  
5 The present invention provides a novel process and its required fluxable materials for building low-cost flip-chip interconnect structures. The novel process involves two fluxable materials, fluxable wafer-level compressive-flow underfill material (WLCFU) and fluxable tacky film, and applies these two materials on a wafer level. The two materials can provide sufficient fluxing capability during solder reflow and significant improvement of the fatigue life of the formed solder interconnects after fully cure.

008280 7777 082800